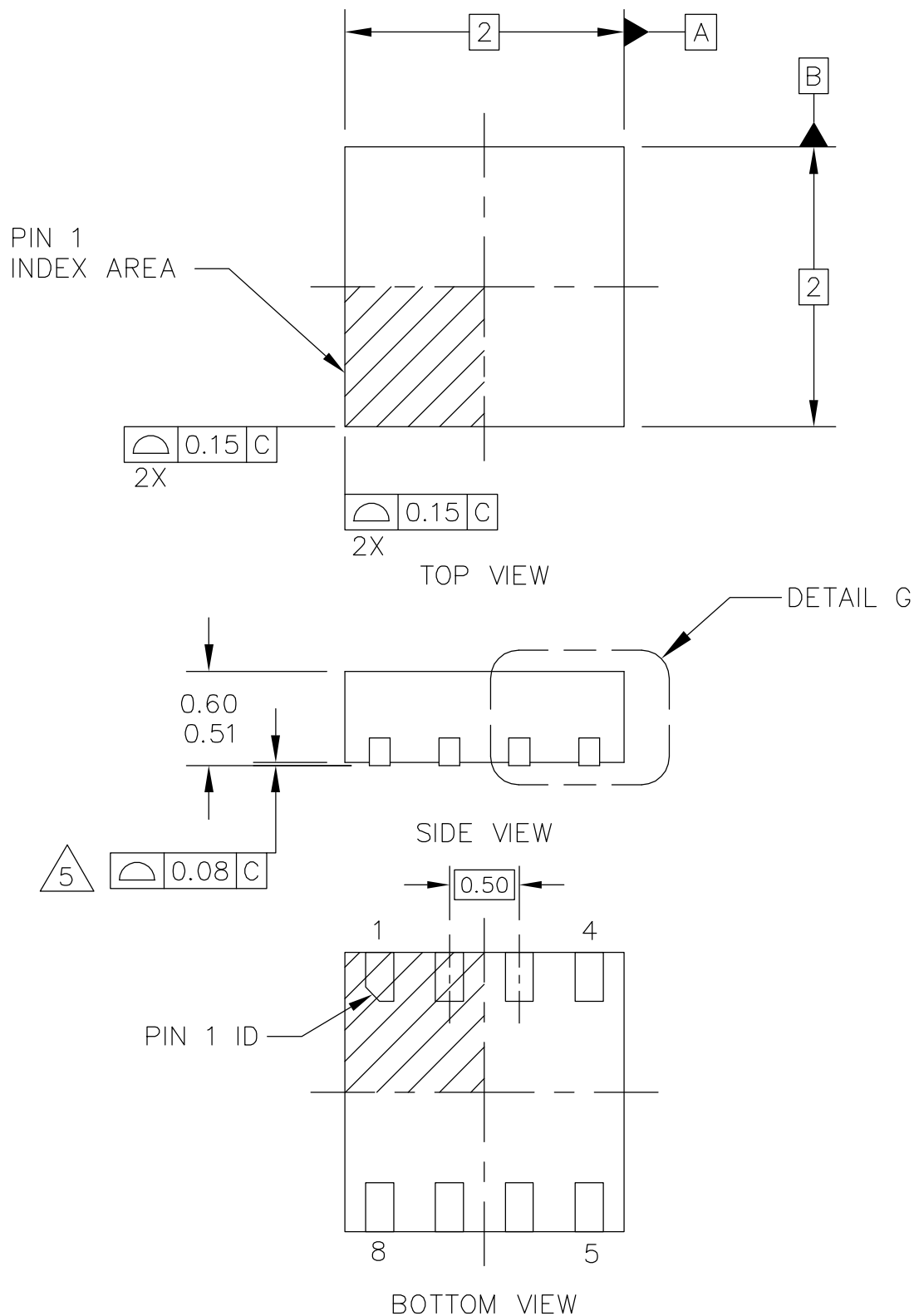
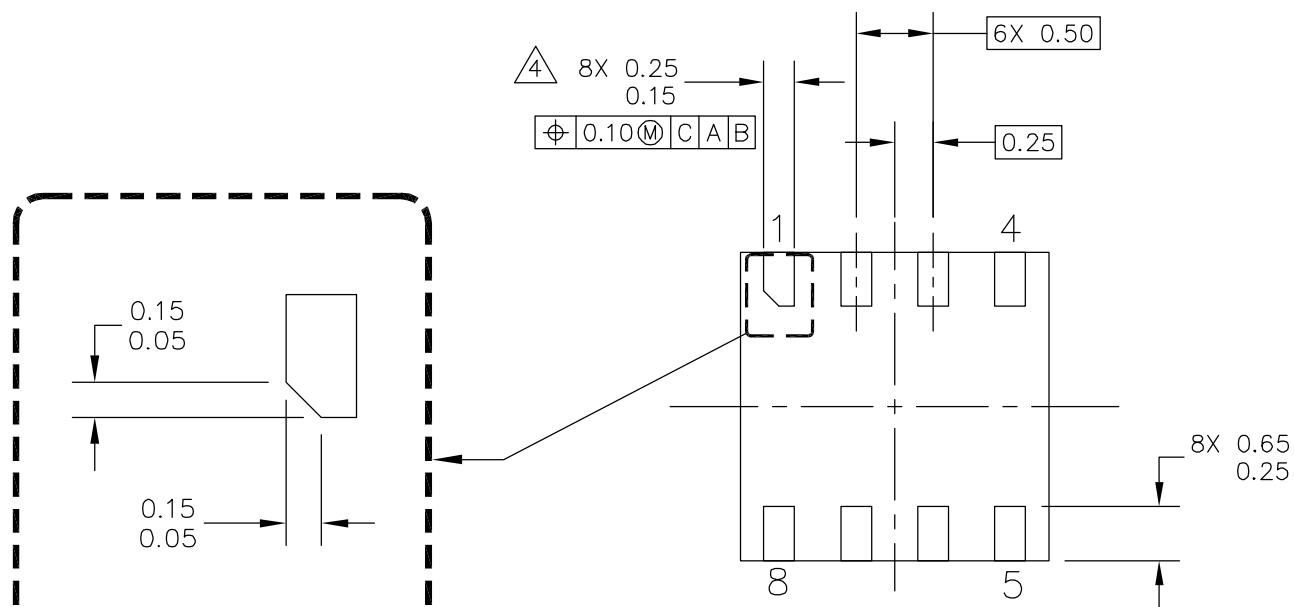


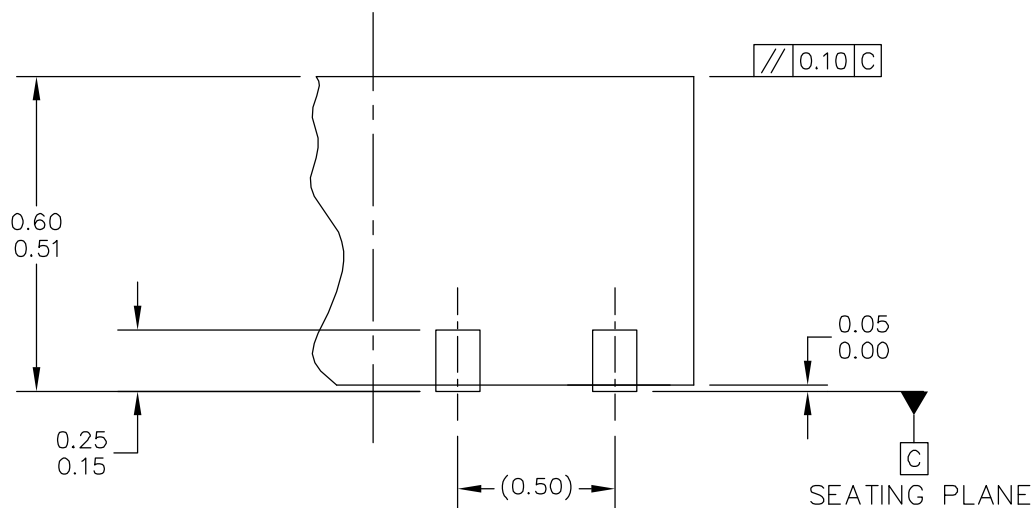


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TITLE: PLASTIC ULTRA-THIN FINE PITCH DUAL FLAT NON-LEADED (UDFN) PACKAGE, 8 TERMINAL, 2 X 2 X 0.65, 0.5 PITCH		DOCUMENT NO: 98ASA10787D	REV: C
		STANDARD: NON-JEDEC	
		SOT1599-1	31 MAR 2016



PIN 1 BACKSIDE IDENTIFIER

DETAIL
BOTTOM VIEW



DETAIL G

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		STANDARD: NON-JEDEC	
		SOT1599-1	31 MAR 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. THE LOCATION OF THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION CONFORM TO JEDEC PUBLICATION 95 SPP-002

4. THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15MM AND 0.30MM FROM THE TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION B SHOULD NOT BE MEASURED IN THAT RADIUS AREA.

5. COPLANARITY APPLIES TO THE TERMINAL AND ALL OTHER BOTTOM SURFACE METALIZATION.

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